

MC11606C6W-SPTLY 1 x 16		6mm Character Height	LCD Module				
Specification							
Version: 2 Date: 25/02/2016							
	Revision						
1 2	12/08/2015 25/02/2016	First issue Modify Precautions in use of LCD Modules &	Static electricity test				

Display Fe	atures		
Character Count	1 x 16		
Appearance	Black on Yellow/Green		
Logic Voltage	5V		
Interface	Parallel		
Font Set	English/Japanese		COHS
Display Mode	Transflective		ampliant
Character Height	6.56mm		omphant
LC Type	STN		
Module Size	85.00 x 28.00 x 13.20mm		
Operating Temperature	-20°C ~ +70°C		
Construction	СОВ	Box Quantity	Weight / Display
LED Backlight	Yellow		

* - For full design functionality, please use this specification in conjunction with the ST7066U specification. (Provided Separately)

Description

Optional Variants							
Fonts	Appearances	Voltage					

General Specification

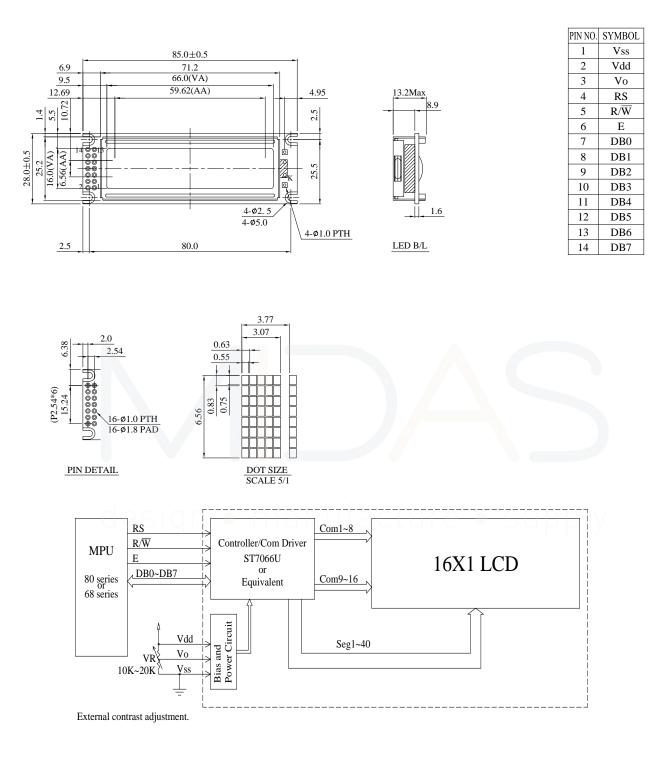
The Features is described as follow:

- Module dimension: 85.0 x 28.0 x 13.2 (max.) mm
- View area: 66.0 x 16.0 mm
- Active area: 59.62 x 6.56 mm
- Number of Characters: 16 characters x 1Lines
- Dot size: 0.55 x 0.75 mm
- Dot pitch: 0.63 x 0.83 mm
- Character size: 3.07 x 6.56 mm
- Character pitch: 3.77 x 6.56 mm
- LCD type: STN Positive, Yellow Green Transflective
- Duty: 1/16
- View direction: 6 o'clock
- Backlight Type: LED, Yellow Green
- IC: ST7066U

Interface Pin Function

Pin No.	Symbol	Level	Description
1	Vss	0V	Ground
2	Vdd	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H:DATA, L:Instruction code
5	R/W	H/L	H: Read (Module> MPU) L: Write(MPU> Module)
6	E	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line

Contour Drawing & Block Diagram



 Character located
 1
 2
 3
 4
 5
 6
 7
 8
 9
 10
 11
 12
 13
 14
 15
 16

 DDRAM address
 00
 01
 02
 03
 04
 05
 06
 07
 40
 41
 42
 43
 44
 45
 46
 47

2-line display mode.

Character Generator ROM Pattern

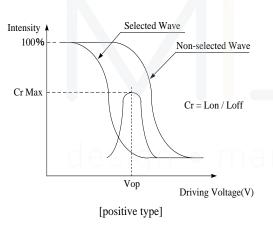
Table.2

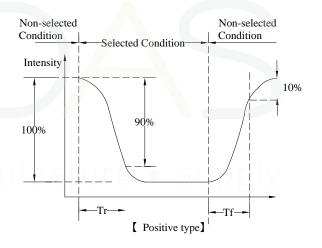
	1		1													
Upper 4 bit Lower 4 bit	LLLL	LLLH	LLHL	LLHH	LHLL	LHLH	LHHL	LHHH	HLLL	HLLH	HLHL	нгнн	HHLL	HHLH	HHHL	нннн
LLLL	CG RAM (1)						•••						-	***	₹ <u>`</u> ₽₿	
LLLH	(2)														•	
LLHL	(3)]				•• !	! ! ! !	[‡]		
LLHH	(4)			•••••		=	:									::-:ª
LHLL	(5)							·			•••		.			
LHLH	(6)			:				II								• • • •
LHHL	(7)			<u>.</u>		l., I		I.,I					•••		pii i	
LHHH	(8)			Y				II								
HLLL	(1)	d	Ľ.						fa	cti	, i i c		••• ••		- I	
HLLH	(2)			•		ا. ۲		•			•••••••	•			1	I
HLHL	(3)												••	.		::::::
HLHH	(4)							-							:-:	
HHLL	(5)			•:							•		·····	:	•:]:-	
HHLH	(6)						[**]					<u>-</u>	-*	••• ••••• [‡]	:]:	
HHHL	(7)				ŀ		[·'']							••••		
нннн	(8)			•				-			• : :	••		:::	ıı	

Optical Characteristics

ltem	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	20	ψ= 180°
	θ	CR≧2	0	_	40	ψ= 0°
View Angle	θ	CR≧2	0	—	30	ψ= 90°
	θ	CR≧2	0	_	30	ψ= 270°
Contrast Ratio	CR	_		3		_
	T rise	_		150	200	ms
Response Time	T fall	_	_	150	200	ms

Definition of Operation Voltage (Vop)





Definition of Response Time (Tr, Tf)

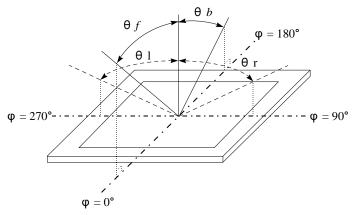
Conditions :

Operating Voltage : Vop

Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR≧2)



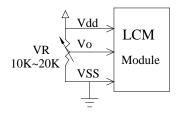
Absolute Maximum Ratings

ltem	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	°C
Storage Temperature	T _{ST}	-30		+80	°C
Input Voltage	Vı	Vss		V _{DD}	V
Supply Voltage For Logic	Vdd-Vss	-0.3	_	7	V
Supply Voltage For LCD	V _{DD} -V _o	-0.3		13	V

Electrical Characteristics

ltem	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	VDD-Vss	-	4.5	5.0	5.5	V
Supply Voltage For LCD		Ta=-20°C	_	_	5.5	V
*Note	VDD-V0	Ta=25°C	4.2	4.35	4.5	V
		Ta=70°C	3.5	_	_	V
Input High Volt.	Vін	_	0.7 V _{DD}	_	V _{DD}	V
Input Low Volt.	VIL	_	Vss	_	0.6	V
Output High Volt.	Vон	_	3.9	_	Vdd	V
Output Low Volt.	Vol		0	_	0.4	V
Supply Current	ldd	V _{DD} =5.0V	1.0	1.2	1.5	mA

* Note: Please design the VOP adjustment circuit on customer's main board

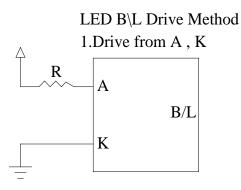


Backlight Information

Specification

PARAMETER	SYMBOL	MIN	ТҮР	МАХ	UNIT	TEST CONDITION
Supply Current	ILED	117	130	156	mA	V=4.1V
Supply Voltage	v	3.9	4.1	4.3	v	_
Reverse Voltage	VR	_	_	8	v	_
Luminance (Without LCD)	IV	216	270	_	CD/M ²	ILED=130mA
Wave Length	λр	569	570	573	nm	ILED=130mA
Life Time	-	-	100000	-	Hr.	ILED≦130mA 25℃,50-60%RH
Color	Yellow Gr	een	1			

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).



Reliability

Content of Reliability Test (Wide temperate	ure, -20℃~70°C)
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Environmental Test							
Test Item	Content of Test	Test Condition	Note				
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2				
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2				
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs					
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1				
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2				
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles					
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3				
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times					

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

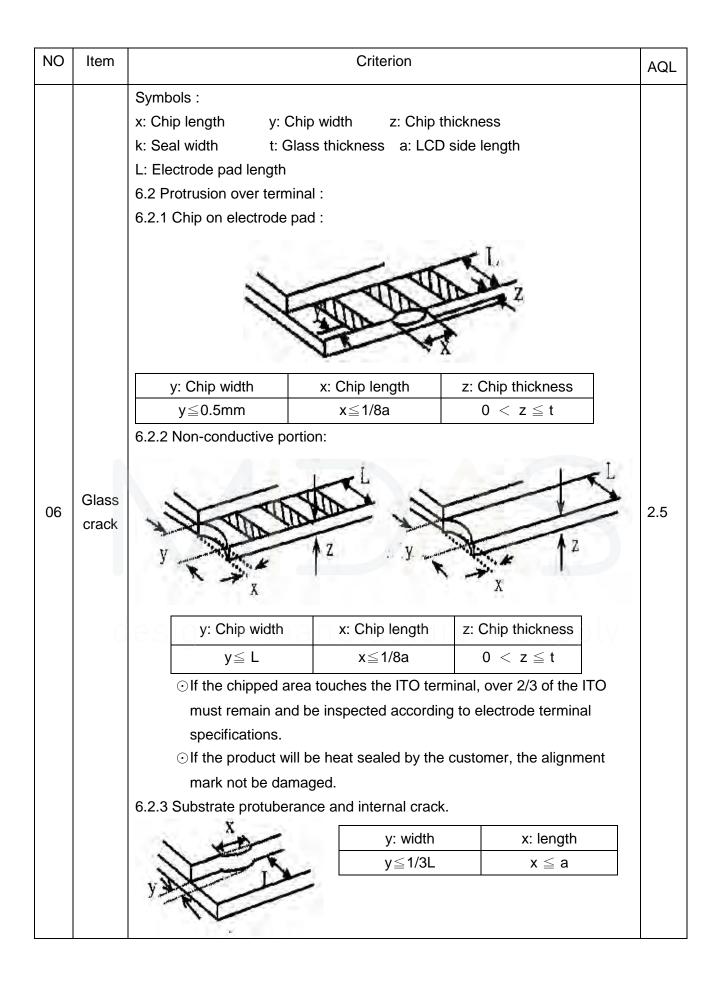
Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

Inspection specification

NO	Item	Criterion				
01	Electrical Testing Black or white	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 2.1 White and black spots on display ≤ 0.25mm, no more than 				
02	spots on LCD (display only)	three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm				
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : Φ=(x + y)/ : 3.2 Line type : (A ↓ ↓ ↓ ↓	2 • •	SIZE Φ ≤ 0.10 0.10<Φ ≤ 0.20 0.20<Φ ≤ 0.25 0.25<Φ	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are vis judge using blac specifications, n to find, must che specify direction	k spot ot easy eck in		Acceptable Q TY Accept no dense 3 2 0 3 3	2.5

NO	Item	Criterion				
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination				
05	Scratches	Symbols Define:x: Chip lengthy: 0k: Seal widtht: 0L: Electrode pad length6.1 General glass chip6.1.1 Chip on panel sur 1.1 Chip on panel sur $1/2$ t $1/2$ t $1/2$ t	Chip width z: Chip t Glass thickness a: LCD	thickness b side length panels: x: Chip length $x \le 1/8a$ $x \le 1/8a$	2.5	
		6.1.2 Corner crack:	y: Chip width Not over viewing area Not exceed 1/3k e chips, x is the total leng	x: Chip length $x \le 1/8a$ $x \le 1/8a$ th of each chip.		



NO	Item	Criterion	AQL	
07	Cracked glass	The LCD with extensive crack is not acceptable.		
08	Backlight elements	8.1 Illumination source flickers when lit.8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.		
09	Bezel	 8.3 Backlight doesn't light or color wrong. 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications. 	0.65 2.5 0.65	
10	PCB · COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 	2.5 2.5 0.65	
		 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB X * Y<=2mm2 	 2.5 2.5 0.65 2.5 2.5 2.5 	
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	 2.5 2.5 2.5 0.65 	

NO	Item	Criterion	AQL
		 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 	2.5
	General appearance	12.3 No contamination, solder residue or solder balls on product.	0.65 2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to	2.5
		sever. 12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12		component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	

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Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) MIDAS have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) MIDAS have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, MIDAS have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

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Material List of Components for RoHs

1. MIDAS hereby declares that all of or part of products (with the mark

"#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2. Process for RoHS requirement : (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow : 250°C,30 seconds Max. ;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C ;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.